Subst. Form PTO-1449 APPLICANT'S INFORMATION DISCLOSURE STATEMENT	Atty. Docket No.: END920000122US1 (IEN-10-5530)	Serial No.: To be assigned 10/657,483
	Applicant: Curcio et al	
	Filing Date: Herewith	Group: 1763

U.S. PATENT DOCUMENTS

Initial*		Document No.	Date	Name	Class	Subcl.	Filing Date
	AA	3,795,047	03/05/74	Abolafia et al	29	625	06/15/72
	AB	5,092,032	03/03/92	Murakimi	29	830	05/15/91
	AC	5,135,606	08/04/92	Kato et al	156	631	12/07/90
	AD	5,200,026	04/06/93	Okabe	156	651	05/15/91
	AE	5,322,593	06/21/94	Hasegawa et al	156	633	11/20/92
	AF	5,624,268	04/29/97	Maeda et al	439	66	01/17/96
	AG	5,819,406	10/13/98	Yoshizawa et al	29	877	07/30/96
	AH	5,984,691	11/16/99	Brodsky et al	439	66	03/10/98
	AI	6,059,579	05/09/00	Kresge et al	439	66	09/24/97
	AJ						
	AK						

FOREIGN PATENT DOCUMENTS

		Document No.	Date	Country	Class	Subcl.	Translation?
	AL						
	AM						
	AN						

OTHER DOCUMENTS

	AO	U.S. Application of Appelt et al for "Manufacturing Methods for Printed Circuit Boards and Printed Circuit Boards Made Thereby", Serial No. 08/968,988 (IBM Docket EN9-97-032)
	AP	U.S. Application of Lauffer et al for "Composite Laminate Circuit Structure and Methods of Interconnecting the Same" (IBM Docket EN9-99-081)
	AQ	IBM Technical Disclosure Bulletin, Vol. 37, No. 02A, "Improved and Cost-Reduced Interposer for Higher-Risk Processes", February, 1994
	AR	"Multi Layer Substrate with Low Coefficient of Thermal Expansion", Kei Nakamura et al, 2000 International Symposium on Microelectronics, pp 235-240
	AS	
	AT	

Examiner: [signature] Date Considered: 9-30-05

*EXAMINER: Initial if reference considered, whether or not citation is in conformation with MPEP 609; draw line through citation if in conformance and not co[illegible] of this form with next communication to applicant.